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#### **EVENTS**

Intelligent Computing and Smart Network, Co-hosted at Nanjing.

Emerging Technology Summit: Co-hosted at Chongqing with CyberC 2020.

# PRELIMINARY CALL FOR PAPERS CyberC 2020

The 12th Int. Conference on Cyber-Enabled Distributed Computing and Knowledge Discovery

Chongqing, China, October 29 - 30, 2020, <a href="www.Cyberc.org">www.Cyberc.org</a>
2020 Theme: Cyber Computing of AI/ML, Blockchain, Big
Data, Image, and 6G

## **Organizer: Chongqing University of Posts and Telecommunications**

Co-hosted by: Nanjing University of Posts & Telecommunications, Zhengzhou University, Guilin University of Electronic Technology, and Chongqing Institute of Engineering

Sponsored by: ZTE (Diamond), Huawei (Platinum), AT&T, InfoBeyond, Tech Mahindra Publication: EI, Journal of <u>Sensor</u> (Special issue)

Scopes: CyberC promotes in-depth exploration of the most recent research and developments in the fields of AI, big data, distributed computing, clouds, cyber security, pervasive computing, mobile computing, Internet of Things, and other cyber-based technologies. Professors, scientists, engineers, and students in these areas are encouraged to participate. CyberC also welcomes industrial participations.

**Chongqing**: The 12th CyberC will be held in Chongqing, China.

Summits: CyberC 2020 co-hosts Emerging Technology Summit (AI/ML, Blockchain, Big Data, Image, and 6G) forum that emphasizes innovative and state-of-art R&D, industry products, specifications, showcases, tutorial, technical transitions, and markets.

**Topics**: The topics of interests include, but not limited to:

- Big Data, AI and Machine Learning
- Internet of things, localization, and distributed computing
- Blockchain theory and applications
- 6G and mobile computing
- Cyber Image and Surveillance
- Cybersecurity and network monitoring
- Signaling processing and wireless Communications
- IoT and cyber physical systems
- Cloud Computing and mobile services
- HPC and Distributed Computing

- Sensors, ICS, Power grids, and communications
- Cyber security and privacy, cyber trust, cyber agility, and cyber assurance

**Co-hosted Workshops:** CyberC 2020 incorporates four workshops:

- Big Data & AI 2020: The 7th International Workshop on Big Data and Artificial Intelligence
- **Security 2020**: The 8th workshop on Cyber Security and Privacy
- Blockchain 2020: The Second workshop on Blockchain
- Cyber Image 2020: The First International Workshop Cyber Image

#### INFORMATION FOR AUTHORS

The CyberC 2020 Proceedings will be published by IEEE CPS. **Full papers** for CyberC 2020 must not exceed 10 pages of IEEE 2-column format, while **short papers** must not exceed 4 pages. Please visit the conference web site at <a href="http://www.cyberc.org">http://www.cyberc.org</a> for precise formatting and submission instructions.

## IMPORTANT DATES

Submission deadline for full (10-page) and/or short (4-page) papers: Aug. 10, 2020 Notification of acceptance: Sept. 10, 2020 Camera-ready deadline: Sept. 20, 2020

#### SPECIAL ISSUE

http://cyberc.org/Callforpapers/SpecialIssue

#### **AUTHOR CONTACTS**

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CyberC 2019 Statistics: 15 Keynotes; Number of submissions: 240, Number of accepted papers: 74, Number of Attendees: 130, Number of Sessions: 10.

**CyberC 2020 Special Issue:** CyberC 2020 provides a special channel for authors to submit your extended version to Journal of Sensors by MDPI. After submission of a CyberC version, you can submit an extended version to the Journal all the time before December 30 2020.

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CyberC 2009 - 2019 Proceeding (Accepted papers): EI, IEEE Xplore, Google Scholar, Scopus, DBLP